506525770 02/26/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chun-Chieh Chan	02/25/2021
Tai-Jung Wu	02/25/2021
Chia-Hao Chang	02/25/2021

RECEIVING PARTY DATA

Name:	Realtek Semiconductor Corp.
Street Address:	2 Innovation Rd. II, Science Park
City:	HsinChu
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17186009

CORRESPONDENCE DATA

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Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	REAP1149USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	02/26/2021

Total Attachments: 6

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PATENT REEL: 055418 FRAME: 0696

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

High Definition Multimedia Interface Transmission Device and Control Method Thereof

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed	on	, or
☐ PCT international application	n number	file	ed on	
The above-identified application was	s made or authorized t	o be made by me.		
I believe that I am the original invent application.	or or an original joint i	nventor of a claim	ed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	Realtek Semicon	ductor Corp.	having a postal add	dress of
2 Innovation Rd. II, Science P	ark, HsinChu 3007	76, Taiwan, R.C).C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			receipt of which is he	ereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, an	nd to any and all impro ation and, in and to, all r any continuations, co	ovements which a Letters Patent to entinuation-in-part,	re disclosed in the be obtained for said divisions, renewals,	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or h this assignment;	encumbrance has	been or will be made	e or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention ecessary or desirable t	n and said Letters to carry out the pro	Patent and said poses thereof.	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.				

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NPO#REA-P1149-USA:0 CUST#109A-174US

Docket No REAP1149USA

LEGAL NAME OF INVENTOR(ASSIGNOR) inventor:

Chun-Chieh Chan

FEB 25 2021 Date:

Signature:

Page 2 of 6

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

High Definition Multimedia Interface Transmission Device and Control Method Thereof

As the below named inventor, I hereby on the section is directed to:	leclare that:				
☑ The attached application, or	☑ The attached application, or				
☐ United States application numb	er	filed on	, or		
□ PCT international application no	ımber	filed on			
The above-identified application was ma	de or authorized to be made	by me.			
I believe that I am the original inventor o application.	I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.				
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.					
In consideration of the payment by Re	altek Semiconductor Co	orp. having a post	al address of		
2 Innovation Rd. II, Science Park	, HsinChu 30076, Taiwa	n, R.O.C.			
(referred to as "ASSIGNEE"below) to I of acknowledged, andfor other good and v		00), the receipt of which	n is hereby		
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.					
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.					
Note: An application data sheet (PTO/S inventive entity, must accompany this fo					

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Docket No REAP1149USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tai-Jung Wu

Date: FEB 25 2021

Signature: Tai-Jung Wu

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

High Definition Multimedia Interface Transmission Device and Control Method Thereof

As the below named inventor, I herei This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	_filed on	, or
☐ PCT international application	number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invente application.	or or an original joint inventor of a	a claimed invention in th	ie
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri			
In consideration of the payment by	Realtek Semiconductor C	orp. having a post	al address of
2 Innovation Rd. II, Science P	ark, HsinChu 30076, Taiwa	n, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		00), the receipt of which	is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements v tion and, in and to, all Letters Pa r any continuations, continuation-	/hich are disclosed in th tent to be obtained for s in-part, divisions, renew	e aid /als,
I hereby covenant that no assignmer entered into which would conflict with		nce has been or will be	made or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal			
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	plication, said invention and said lecessary or desirable to carry out	Letters Patent and said the proposes thereof.	
Note: An application data sheet (PTC inventive entity, must accompany thi			

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NPO#REA-P1149-USA:0 CUST#109A-174US

Docket No REAP1149USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chia-Hao Chang

Date: FEB 25 2021

NPO#REA-P1149-USA:0 CUST#109A-174US

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F#NPO-P0002E-US1201 DSB0-109U032644

PATENT REEL: 055418 FRAME: 0702

RECORDED: 02/26/2021